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What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

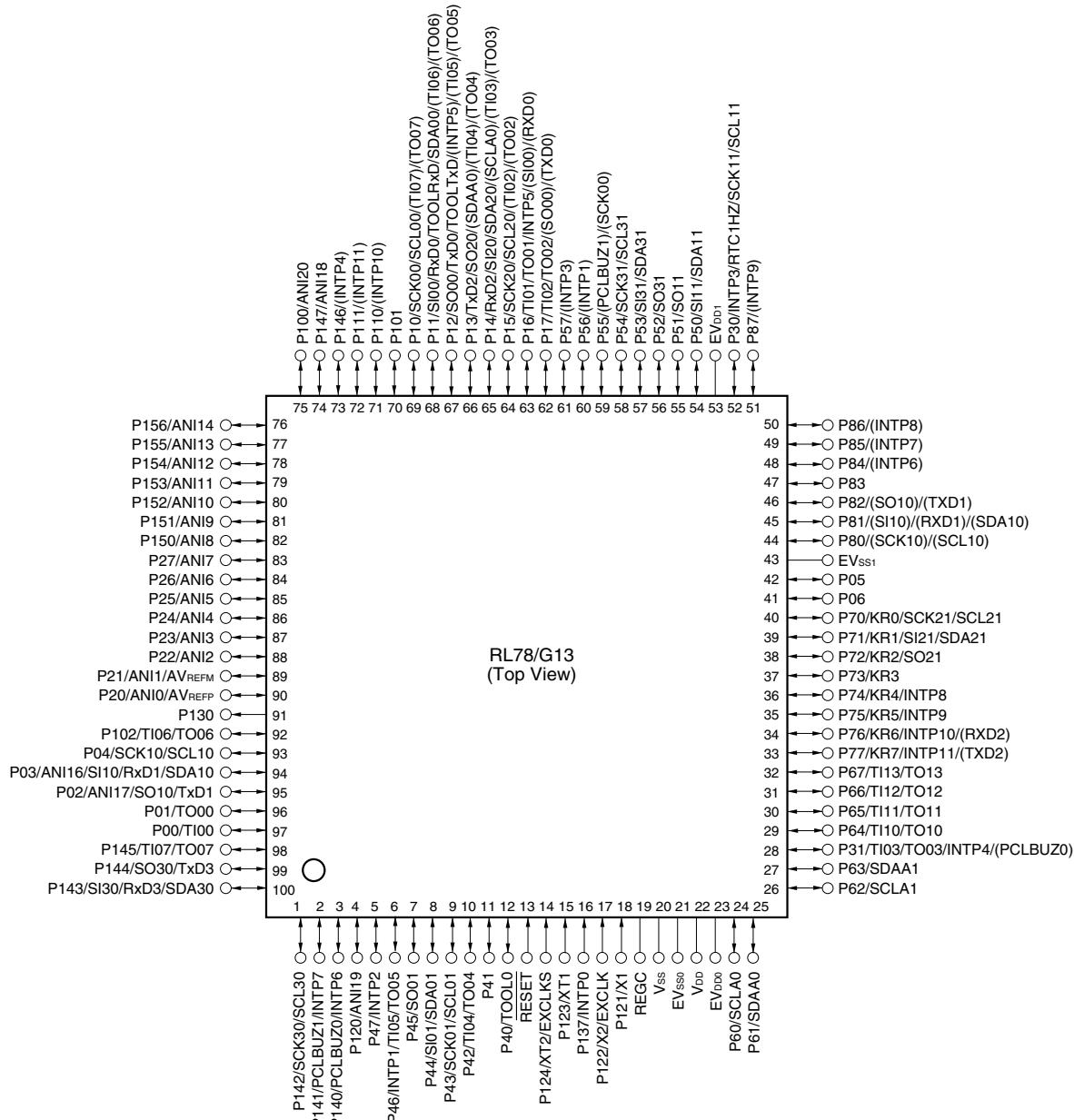
Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	RL78
Core Size	16-Bit
Speed	32MHz
Connectivity	CSI, I ² C, LINbus, UART/USART
Peripherals	DMA, LVD, POR, PWM, WDT
Number of I/O	48
Program Memory Size	256KB (256K x 8)
Program Memory Type	FLASH
EEPROM Size	8K x 8
RAM Size	20K x 8
Voltage - Supply (Vcc/Vdd)	1.6V ~ 5.5V
Data Converters	A/D 12x8/10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	64-LFQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f100ljafb-50

1.3.13 100-pin products

- 100-pin plastic LQFP (14 × 14 mm, 0.5 mm pitch)

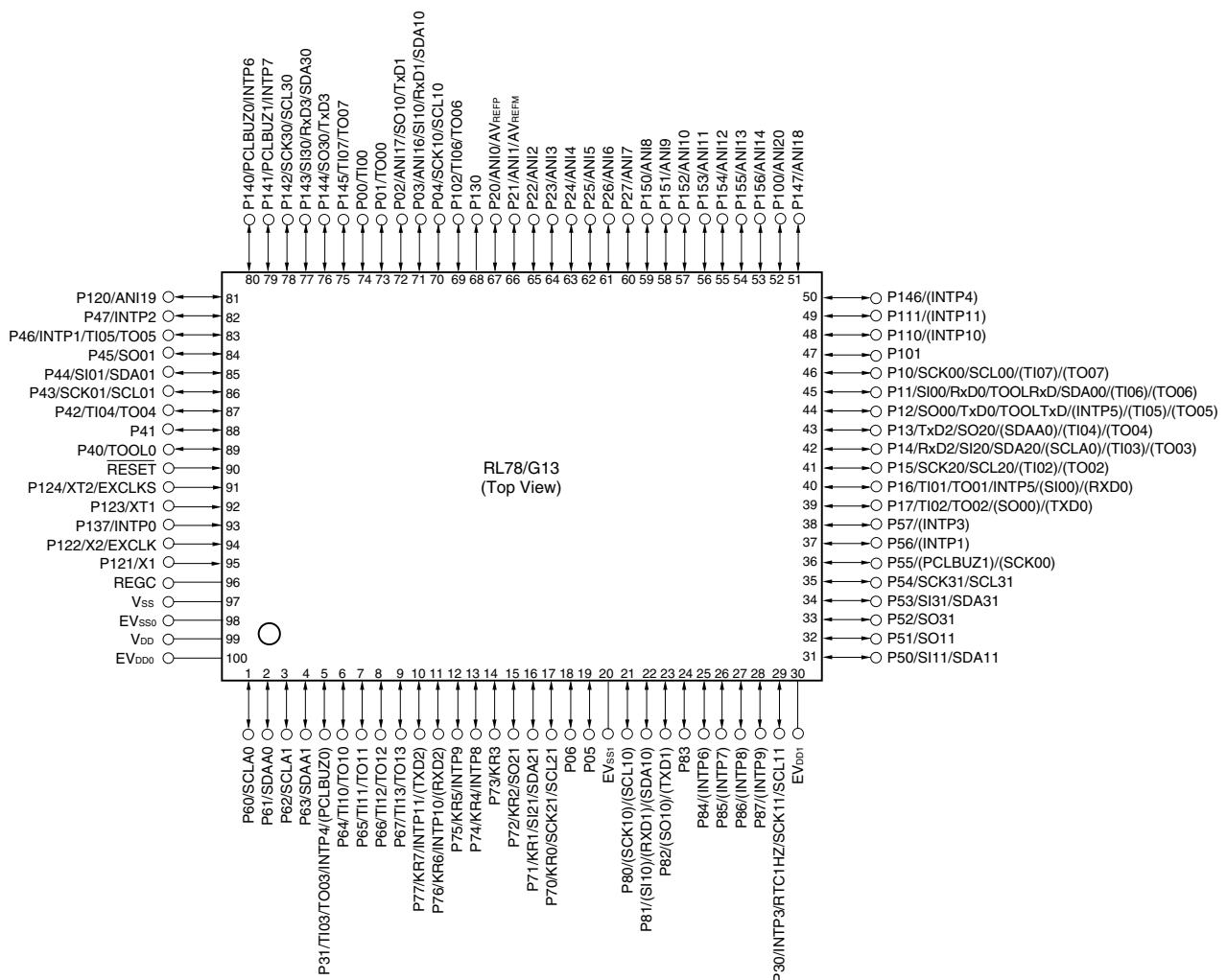


2. Make V_{dd} pin the potential that is higher than EV_{dd0}, EV_{dd1} pins (EV_{dd0} = EV_{dd1}).
3. Connect the REGC pin to V_{ss} via a capacitor (0.47 to 1 μ F).

Remarks 1. For pin identification, see 1.4 Pin Identification.

2. When using the microcontroller for an application where the noise generated inside the microcontroller must be reduced, it is recommended to supply separate powers to the V_{dd}, EV_{dd0} and EV_{dd1} pins and connect the V_{ss}, EV_{ss0} and EV_{ss1} pins to separate ground lines.
3. Functions in parentheses in the above figure can be assigned via settings in the peripheral I/O redirection register (PIOR). Refer to **Figure 4-8 Format of Peripheral I/O Redirection Register (PIOR)** in the RL78/G13 User's Manual.

- 100-pin plastic LQFP (14 × 20 mm, 0.65 mm pitch)



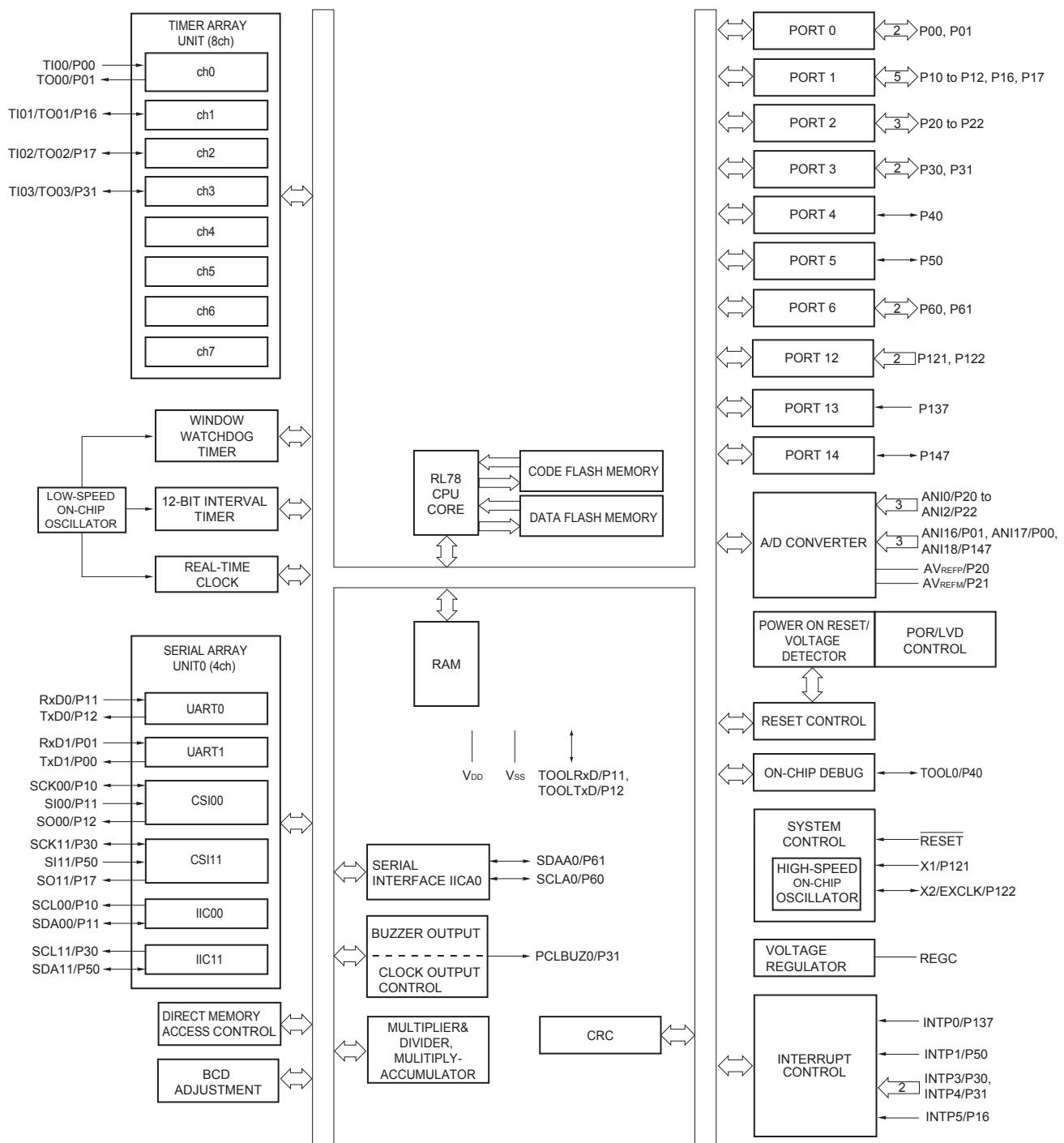
Cautions 1. Make EV_{SS0}, EV_{SS1} pins the same potential as V_{SS} pin.

2. Make V_{DD} pin the potential that is higher than EV_{DD0}, EV_{DD1} pins (EV_{DD0} = EV_{DD1}).
3. Connect the REGC pin to V_{SS} via a capacitor (0.47 to 1 μ F).

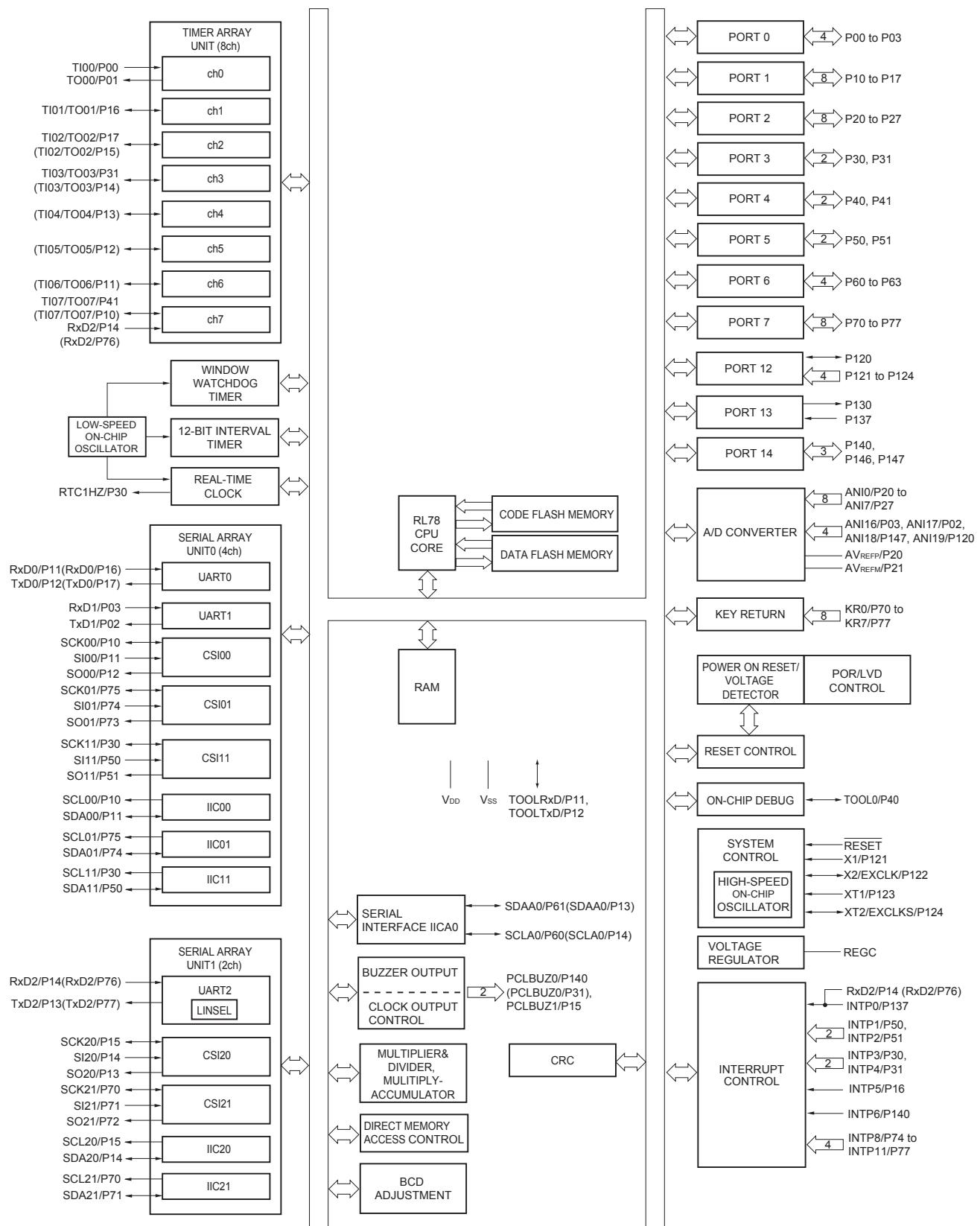
Remarks 1. For pin identification, see **1.4 Pin Identification**.

2. When using the microcontroller for an application where the noise generated inside the microcontroller must be reduced, it is recommended to supply separate powers to the V_{DD}, EV_{DD0} and EV_{DD1} pins and connect the V_{SS}, EV_{SS0} and EV_{SS1} pins to separate ground lines.
3. Functions in parentheses in the above figure can be assigned via settings in the peripheral I/O redirection register (PIOR). Refer to **Figure 4-8 Format of Peripheral I/O Redirection Register (PIOR)** in the RL78/G13 User's Manual.

1.5.2 24-pin products



1.5.10 52-pin products



Remark Functions in parentheses in the above figure can be assigned via settings in the peripheral I/O redirection register (PIOR). Refer to **Figure 4-8 Format of Peripheral I/O Redirection Register (PIOR)** in the RL78/G13 User's Manual.

2. The number of PWM outputs varies depending on the setting of channels in use (the number of masters and slaves) (see **6.9.3 Operation as multiple PWM output function** in the RL78/G13 User's Manual).

(2/2)

Item	80-pin		100-pin		128-pin	
	R5F100Mx	R5F101Mx	R5F100Px	R5F101Px	R5F100Sx	R5F101Sx
Clock output/buzzer output	2		2		2	
	<ul style="list-style-type: none"> • 2.44 kHz, 4.88 kHz, 9.76 kHz, 1.25 MHz, 2.5 MHz, 5 MHz, 10 MHz (Main system clock: $f_{MAIN} = 20$ MHz operation) • 256 Hz, 512 Hz, 1.024 kHz, 2.048 kHz, 4.096 kHz, 8.192 kHz, 16.384 kHz, 32.768 kHz (Subsystem clock: $f_{SUB} = 32.768$ kHz operation) 					
8/10-bit resolution A/D converter	17 channels		20 channels		26 channels	
Serial interface	[80-pin, 100-pin, 128-pin products]		<ul style="list-style-type: none"> • CSI: 2 channels/simplified I²C: 2 channels/UART: 1 channel • CSI: 2 channels/simplified I²C: 2 channels/UART: 1 channel • CSI: 2 channels/simplified I²C: 2 channels/UART (UART supporting LIN-bus): 1 channel • CSI: 2 channels/simplified I²C: 2 channels/UART: 1 channel 			
I ² C bus	2 channels		2 channels		2 channels	
Multiplier and divider/multiply-accumulator	<ul style="list-style-type: none"> • $16 \text{ bits} \times 16 \text{ bits} = 32 \text{ bits}$ (Unsigned or signed) • $32 \text{ bits} \div 32 \text{ bits} = 32 \text{ bits}$ (Unsigned) • $16 \text{ bits} \times 16 \text{ bits} + 32 \text{ bits} = 32 \text{ bits}$ (Unsigned or signed) 					
DMA controller	4 channels					
Vectorized interrupt sources	Internal	37		37		41
	External	13		13		13
Key interrupt	8		8		8	
Reset	<ul style="list-style-type: none"> • Reset by $\overline{\text{RESET}}$ pin • Internal reset by watchdog timer • Internal reset by power-on-reset • Internal reset by voltage detector • Internal reset by illegal instruction execution ^{Note} • Internal reset by RAM parity error • Internal reset by illegal-memory access 					
Power-on-reset circuit	<ul style="list-style-type: none"> • Power-on-reset: 1.51 V (TYP.) • Power-down-reset: 1.50 V (TYP.) 					
Voltage detector	<ul style="list-style-type: none"> • Rising edge : 1.67 V to 4.06 V (14 stages) • Falling edge : 1.63 V to 3.98 V (14 stages) 					
On-chip debug function	Provided					
Power supply voltage	$V_{DD} = 1.6$ to 5.5 V ($T_A = -40$ to $+85^\circ\text{C}$) $V_{DD} = 2.4$ to 5.5 V ($T_A = -40$ to $+105^\circ\text{C}$)					
Operating ambient temperature	$T_A = 40$ to $+85^\circ\text{C}$ (A: Consumer applications, D: Industrial applications) $T_A = 40$ to $+105^\circ\text{C}$ (G: Industrial applications)					

Note The illegal instruction is generated when instruction code FFH is executed.

Reset by the illegal instruction execution not issued by emulation with the in-circuit emulator or on-chip debug emulator.

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($T_A = -40$ to $+85^\circ\text{C}$, $1.6 \text{ V} \leq EV_{DD0} = EV_{DD1} \leq V_{DD} \leq 5.5 \text{ V}$, $V_{SS} = EV_{SS0} = EV_{SS1} = 0 \text{ V}$) (5/5)

Items	Symbol	Conditions		MIN.	TYP.	MAX.	Unit		
Input leakage current, high	I_{LIH1}	P00 to P07, P10 to P17, P30 to P37, P40 to P47, P50 to P57, P60 to P67, P70 to P77, P80 to P87, P90 to P97, P100 to P106, P110 to P117, P120, P125 to P127, P140 to P147		$V_I = EV_{DD0}$		1	μA		
	I_{LIH2}	P20 to P27, P137, P150 to P156, RESET		$V_I = V_{DD}$		1	μA		
	I_{LIH3}	P121 to P124 (X1, X2, XT1, XT2, EXCLK, EXCLKS)		$V_I = V_{DD}$	In input port or external clock input	1	μA		
						10	μA		
Input leakage current, low	I_{LIL1}	P00 to P07, P10 to P17, P30 to P37, P40 to P47, P50 to P57, P60 to P67, P70 to P77, P80 to P87, P90 to P97, P100 to P106, P110 to P117, P120, P125 to P127, P140 to P147		$V_I = EV_{SS0}$		-1	μA		
	I_{LIL2}	P20 to P27, P137, P150 to P156, RESET		$V_I = V_{SS}$		-1	μA		
	I_{LIL3}	P121 to P124 (X1, X2, XT1, XT2, EXCLK, EXCLKS)		$V_I = V_{SS}$	In input port or external clock input	-1	μA		
						-10	μA		
On-chip pll-up resistance	R_u	P00 to P07, P10 to P17, P30 to P37, P40 to P47, P50 to P57, P64 to P67, P70 to P77, P80 to P87, P90 to P97, P100 to P106, P110 to P117, P120, P125 to P127, P140 to P147		$V_I = EV_{SS0}$, In input port		10	20	100	$k\Omega$

Remark Unless specified otherwise, the characteristics of alternate-function pins are the same as those of the port pins.

(2) Flash ROM: 96 to 256 KB of 30- to 100-pin products

 $(T_A = -40$ to $+85^\circ\text{C}$, $1.6 \text{ V} \leq EV_{DD0} = EV_{DD1} \leq V_{DD} \leq 5.5 \text{ V}$, $V_{SS} = EV_{SS0} = EV_{SS1} = 0 \text{ V}$) (2/2)

Parameter	Symbol	Conditions			MIN.	TYP.	MAX.	Unit	
Supply current <small>Note 1</small>	$I_{DD2}^{Note 2}$	HALT mode	HS (high-speed main) mode ^{Note 7}	$f_{IH} = 32 \text{ MHz}^{Note 4}$	$V_{DD} = 5.0 \text{ V}$		0.62	1.86 mA	
				$V_{DD} = 3.0 \text{ V}$			0.62	1.86 mA	
			$f_{IH} = 24 \text{ MHz}^{Note 4}$	$V_{DD} = 5.0 \text{ V}$			0.50	1.45 mA	
				$V_{DD} = 3.0 \text{ V}$			0.50	1.45 mA	
			$f_{IH} = 16 \text{ MHz}^{Note 4}$	$V_{DD} = 5.0 \text{ V}$			0.44	1.11 mA	
				$V_{DD} = 3.0 \text{ V}$			0.44	1.11 mA	
		LS (low-speed main) mode ^{Note 7}	$f_{IH} = 8 \text{ MHz}^{Note 4}$	$V_{DD} = 3.0 \text{ V}$			290	620 μA	
				$V_{DD} = 2.0 \text{ V}$			290	620 μA	
		LV (low-voltage main) mode <small>Note 7</small>	$f_{IH} = 4 \text{ MHz}^{Note 4}$	$V_{DD} = 3.0 \text{ V}$			440	680 μA	
				$V_{DD} = 2.0 \text{ V}$			440	680 μA	
		HS (high-speed main) mode ^{Note 7}	$f_{MX} = 20 \text{ MHz}^{Note 3}$, $V_{DD} = 5.0 \text{ V}$	Square wave input			0.31	1.08 mA	
				Resonator connection			0.48	1.28 mA	
			$f_{MX} = 20 \text{ MHz}^{Note 3}$, $V_{DD} = 3.0 \text{ V}$	Square wave input			0.31	1.08 mA	
				Resonator connection			0.48	1.28 mA	
			$f_{MX} = 10 \text{ MHz}^{Note 3}$, $V_{DD} = 5.0 \text{ V}$	Square wave input			0.21	0.63 mA	
				Resonator connection			0.28	0.71 mA	
			$f_{MX} = 10 \text{ MHz}^{Note 3}$, $V_{DD} = 3.0 \text{ V}$	Square wave input			0.21	0.63 mA	
				Resonator connection			0.28	0.71 mA	
		LS (low-speed main) mode ^{Note 7}	$f_{MX} = 8 \text{ MHz}^{Note 3}$, $V_{DD} = 3.0 \text{ V}$	Square wave input			110	360 μA	
				Resonator connection			160	420 μA	
			$f_{MX} = 8 \text{ MHz}^{Note 3}$, $V_{DD} = 2.0 \text{ V}$	Square wave input			110	360 μA	
				Resonator connection			160	420 μA	
		Subsystem clock operation	$f_{SUB} = 32.768 \text{ kHz}^{Note 5}$ $T_A = -40^\circ\text{C}$	Square wave input			0.28	0.61 μA	
				Resonator connection			0.47	0.80 μA	
			$f_{SUB} = 32.768 \text{ kHz}^{Note 5}$ $T_A = +25^\circ\text{C}$	Square wave input			0.34	0.61 μA	
				Resonator connection			0.53	0.80 μA	
			$f_{SUB} = 32.768 \text{ kHz}^{Note 5}$ $T_A = +50^\circ\text{C}$	Square wave input			0.41	2.30 μA	
				Resonator connection			0.60	2.49 μA	
			$f_{SUB} = 32.768 \text{ kHz}^{Note 5}$ $T_A = +70^\circ\text{C}$	Square wave input			0.64	4.03 μA	
				Resonator connection			0.83	4.22 μA	
			$f_{SUB} = 32.768 \text{ kHz}^{Note 5}$ $T_A = +85^\circ\text{C}$	Square wave input			1.09	8.04 μA	
				Resonator connection			1.28	8.23 μA	
$I_{DD3}^{Note 6}$	STOP mode ^{Note 8}	$T_A = -40^\circ\text{C}$					0.19	0.52 μA	
		$T_A = +25^\circ\text{C}$					0.25	0.52 μA	
		$T_A = +50^\circ\text{C}$					0.32	2.21 μA	
		$T_A = +70^\circ\text{C}$					0.55	3.94 μA	
		$T_A = +85^\circ\text{C}$					1.00	7.95 μA	

(Notes and Remarks are listed on the next page.)

(6) Communication at different potential (1.8 V, 2.5 V, 3 V) (UART mode) (2/2)

 $(T_A = -40$ to $+85^\circ\text{C}$, $1.8 \text{ V} \leq EV_{DD0} = EV_{DD1} \leq V_{DD} \leq 5.5 \text{ V}$, $V_{SS} = EV_{SS0} = EV_{SS1} = 0 \text{ V}$)

Parameter	Symbol	Conditions		HS (high-speed main) Mode		LS (low-speed main) Mode		LV (low-voltage main) Mode		Unit
				MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
Transfer rate	Transmission	4.0 V $\leq EV_{DD0} \leq 5.5$ V, 2.7 V $\leq V_b \leq 4.0$ V	Theoretical value of the maximum transfer rate $C_b = 50 \text{ pF}$, $R_b = 1.4 \text{ k}\Omega$, $V_b = 2.7 \text{ V}$	Note 1		Note 1		Note 1		bps
				2.8 Note 2		2.8 Note 2		2.8 Note 2		Mbps
				Note 3		Note 3		Note 3		bps
		2.7 V $\leq EV_{DD0} < 4.0$ V, 2.3 V $\leq V_b \leq 2.7$ V	Theoretical value of the maximum transfer rate $C_b = 50 \text{ pF}$, $R_b = 2.7 \text{ k}\Omega$, $V_b = 2.3 \text{ V}$	1.2 Note 4		1.2 Note 4		1.2 Note 4		Mbps
		1.8 V $\leq EV_{DD0} < 3.3$ V, 1.6 V $\leq V_b \leq 2.0$ V	Theoretical value of the maximum transfer rate $C_b = 50 \text{ pF}$, $R_b = 5.5 \text{ k}\Omega$, $V_b = 1.6 \text{ V}$	Notes 5, 6		Notes 5, 6		Notes 5, 6		bps
				0.43 Note 7		0.43 Note 7		0.43 Note 7		Mbps

Notes 1. The smaller maximum transfer rate derived by using $f_{MCK}/6$ or the following expression is the valid maximum transfer rate.

Expression for calculating the transfer rate when $4.0 \text{ V} \leq EV_{DD0} \leq 5.5 \text{ V}$ and $2.7 \text{ V} \leq V_b \leq 4.0 \text{ V}$

$$\text{Maximum transfer rate} = \frac{1}{\{-C_b \times R_b \times \ln(1 - \frac{2.2}{V_b})\} \times 3} \text{ [bps]}$$

$$\text{Baud rate error (theoretical value)} = \frac{\frac{1}{\text{Transfer rate} \times 2} - \{-C_b \times R_b \times \ln(1 - \frac{2.2}{V_b})\}}{\left(\frac{1}{\text{Transfer rate}}\right) \times \text{Number of transferred bits}} \times 100 \text{ [%]}$$

* This value is the theoretical value of the relative difference between the transmission and reception sides.

- 2.** This value as an example is calculated when the conditions described in the “Conditions” column are met. Refer to Note 1 above to calculate the maximum transfer rate under conditions of the customer.

3. The smaller maximum transfer rate derived by using fmck/6 or the following expression is the valid maximum transfer rate.

Expression for calculating the transfer rate when 2.7 V ≤ EV_{DD0} < 4.0 V and 2.3 V ≤ V_b ≤ 2.7 V

$$\text{Maximum transfer rate} = \frac{1}{\{-C_b \times R_b \times \ln(1 - \frac{2.0}{V_b})\} \times 3} \text{ [bps]}$$

$$\text{Baud rate error (theoretical value)} = \frac{\frac{1}{\text{Transfer rate} \times 2} - \{-C_b \times R_b \times \ln(1 - \frac{2.0}{V_b})\}}{\left(\frac{1}{\text{Transfer rate}}\right) \times \text{Number of transferred bits}} \times 100 [\%]$$

* This value is the theoretical value of the relative difference between the transmission and reception sides.

4. This value as an example is calculated when the conditions described in the “Conditions” column are met. Refer to Note 3 above to calculate the maximum transfer rate under conditions of the customer.
5. Use it with EV_{DD0} ≥ V_b.
6. The smaller maximum transfer rate derived by using fmck/6 or the following expression is the valid maximum transfer rate.

Expression for calculating the transfer rate when 1.8 V ≤ EV_{DD0} < 3.3 V and 1.6 V ≤ V_b ≤ 2.0 V

$$\text{Maximum transfer rate} = \frac{1}{\{-C_b \times R_b \times \ln(1 - \frac{1.5}{V_b})\} \times 3} \text{ [bps]}$$

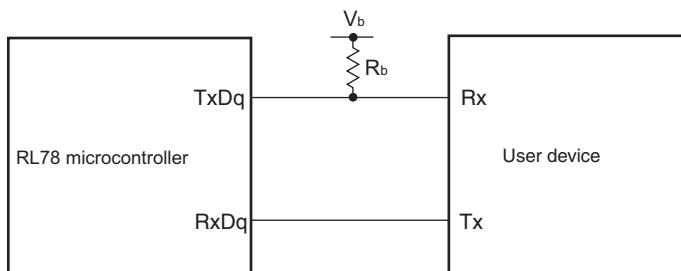
$$\text{Baud rate error (theoretical value)} = \frac{\frac{1}{\text{Transfer rate} \times 2} - \{-C_b \times R_b \times \ln(1 - \frac{1.5}{V_b})\}}{\left(\frac{1}{\text{Transfer rate}}\right) \times \text{Number of transferred bits}} \times 100 [\%]$$

* This value is the theoretical value of the relative difference between the transmission and reception sides.

7. This value as an example is calculated when the conditions described in the “Conditions” column are met. Refer to Note 6 above to calculate the maximum transfer rate under conditions of the customer.

Caution Select the TTL input buffer for the RxDq pin and the N-ch open drain output (V_{DD} tolerance (When 20- to 52-pin products)/EV_{DD} tolerance (When 64- to 128-pin products)) mode for the TxDq pin by using port input mode register g (PIMg) and port output mode register g (POMg). For V_{IH} and V_{IL}, see the DC characteristics with TTL input buffer selected.

UART mode connection diagram (during communication at different potential)



**(8) Communication at different potential (1.8 V, 2.5 V, 3 V) (CSI mode) (master mode, SCKp... internal clock output)
(1/3)**

($T_A = -40$ to $+85^\circ\text{C}$, $1.8 \text{ V} \leq EV_{DD0} = EV_{DD1} \leq V_{DD} \leq 5.5 \text{ V}$, $V_{SS} = EV_{SS0} = EV_{SS1} = 0 \text{ V}$)

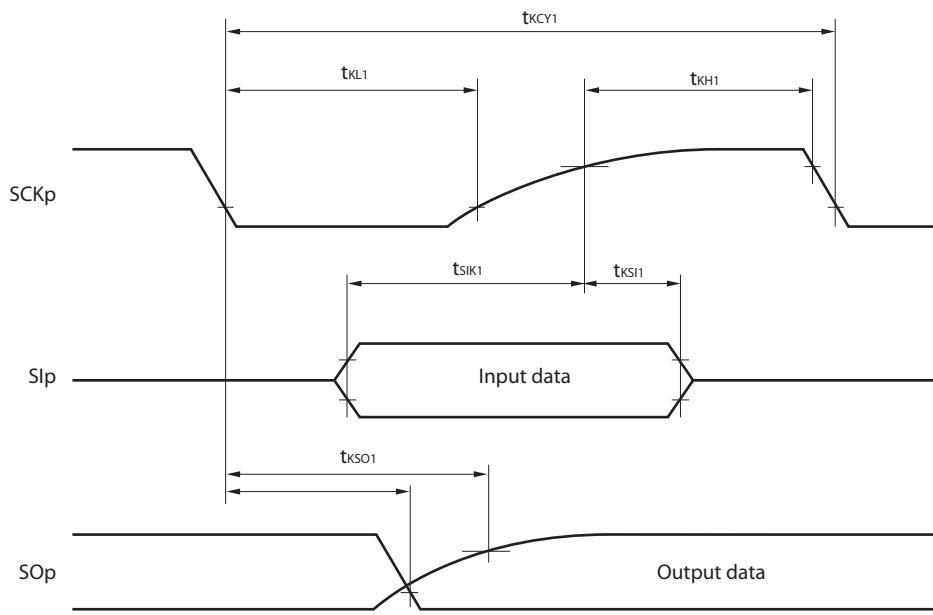
Parameter	Symbol	Conditions		HS (high-speed main) Mode		LS (low-speed main) Mode		LV (low-voltage main) Mode		Unit
				MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
SCKp cycle time	t _{KCY1}	t _{KCY1} ≥ 4/f _{CLK}	4.0 V ≤ EV _{DD0} ≤ 5.5 V, 2.7 V ≤ V _b ≤ 4.0 V, C _b = 30 pF, R _b = 1.4 kΩ	300		1150		1150		ns
			2.7 V ≤ EV _{DD0} < 4.0 V, 2.3 V ≤ V _b ≤ 2.7 V, C _b = 30 pF, R _b = 2.7 kΩ	500		1150		1150		ns
			1.8 V ≤ EV _{DD0} < 3.3 V, 1.6 V ≤ V _b ≤ 2.0 V ^{Note} , C _b = 30 pF, R _b = 5.5 kΩ	1150		1150		1150		ns
SCKp high-level width	t _{Kh1}	4.0 V ≤ EV _{DD0} ≤ 5.5 V, 2.7 V ≤ V _b ≤ 4.0 V, C _b = 30 pF, R _b = 1.4 kΩ	t _{KCY1} /2 – 75		t _{KCY1} /2 – 75		t _{KCY1} /2 – 75			ns
		2.7 V ≤ EV _{DD0} < 4.0 V, 2.3 V ≤ V _b ≤ 2.7 V, C _b = 30 pF, R _b = 2.7 kΩ	t _{KCY1} /2 – 170		t _{KCY1} /2 – 170		t _{KCY1} /2 – 170			ns
		1.8 V ≤ EV _{DD0} < 3.3 V, 1.6 V ≤ V _b ≤ 2.0 V ^{Note} , C _b = 30 pF, R _b = 5.5 kΩ	t _{KCY1} /2 – 458		t _{KCY1} /2 – 458		t _{KCY1} /2 – 458			ns
SCKp low-level width	t _{KL1}	4.0 V ≤ EV _{DD0} ≤ 5.5 V, 2.7 V ≤ V _b ≤ 4.0 V, C _b = 30 pF, R _b = 1.4 kΩ	t _{KCY1} /2 – 12		t _{KCY1} /2 – 50		t _{KCY1} /2 – 50			ns
		2.7 V ≤ EV _{DD0} < 4.0 V, 2.3 V ≤ V _b ≤ 2.7 V, C _b = 30 pF, R _b = 2.7 kΩ	t _{KCY1} /2 – 18		t _{KCY1} /2 – 50		t _{KCY1} /2 – 50			ns
		1.8 V ≤ EV _{DD0} < 3.3 V, 1.6 V ≤ V _b ≤ 2.0 V ^{Note} , C _b = 30 pF, R _b = 5.5 kΩ	t _{KCY1} /2 – 50		t _{KCY1} /2 – 50		t _{KCY1} /2 – 50			ns

Note Use it with $EV_{DD0} \geq V_b$.

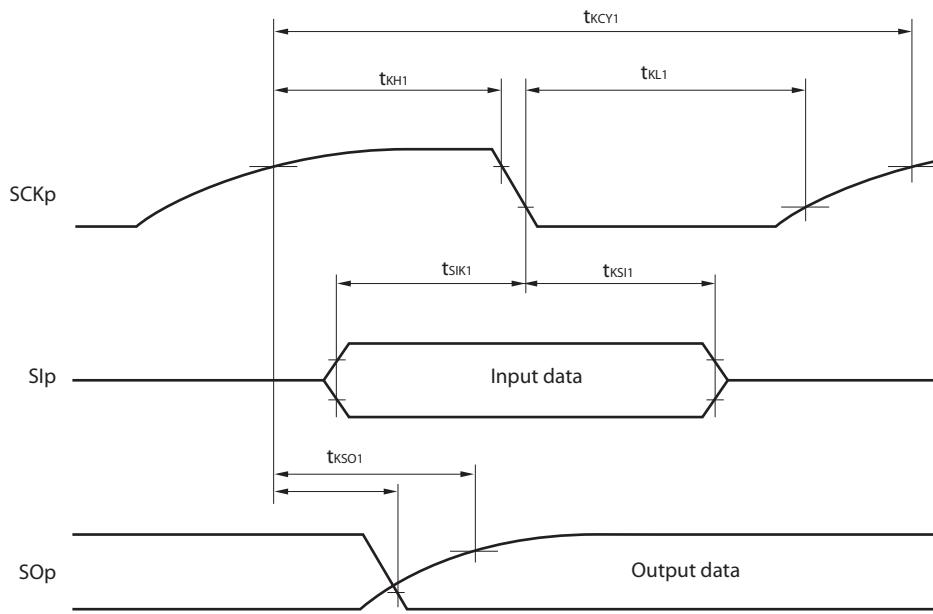
Caution Select the TTL input buffer for the S_{Op} pin and the N-ch open drain output (V_{DD} tolerance (When 20- to 52-pin products)/EV_{DD} tolerance (When 64- to 128-pin products)) mode for the S_{Op} pin and SCKp pin by using port input mode register g (PIMg) and port output mode register g (POMg). For V_{IH} and V_{IL}, see the DC characteristics with TTL input buffer selected.

(Remarks are listed two pages after the next page.)

CSI mode serial transfer timing (master mode) (during communication at different potential)
(When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1.)



CSI mode serial transfer timing (master mode) (during communication at different potential)
(When DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.)



- Remarks**
1. p: CSI number ($p = 00, 01, 10, 20, 30, 31$), m: Unit number, n: Channel number ($mn = 00, 01, 02, 10, 12, 13$), g: PIM and POM number ($g = 0, 1, 4, 5, 8, 14$)
 2. CSI01 of 48-, 52-, 64-pin products, and CSI11 and CSI21 cannot communicate at different potential.
Use other CSI for communication at different potential.

2.6 Analog Characteristics

2.6.1 A/D converter characteristics

Classification of A/D converter characteristics

Input channel	Reference Voltage		
	Reference voltage (+) = AV_{REFP}	Reference voltage (+) = V_{DD}	Reference voltage (+) = V_{BGR}
Reference voltage (-) = AV_{REFM}	Reference voltage (-) = V_{SS}	Reference voltage (-) = AV_{REFM}	Reference voltage (-) = AV_{REFM}
ANI0 to ANI14	Refer to 2.6.1 (1).	Refer to 2.6.1 (3).	Refer to 2.6.1 (4).
ANI16 to ANI26	Refer to 2.6.1 (2).		
Internal reference voltage Temperature sensor output voltage	Refer to 2.6.1 (1).		—

(1) When reference voltage (+) = AV_{REFP} /ANI0 (ADREFP1 = 0, ADREFP0 = 1), reference voltage (-) = AV_{REFM} /ANI1 (ADREFM = 1), target pin : ANI2 to ANI14, internal reference voltage, and temperature sensor output voltage

($T_A = -40$ to $+85^\circ\text{C}$, $1.6 \text{ V} \leq \text{AV}_{\text{REFP}} \leq \text{V}_{\text{DD}} \leq 5.5 \text{ V}$, $\text{V}_{\text{SS}} = 0 \text{ V}$, Reference voltage (+) = AV_{REFP} , Reference voltage (-) = $\text{AV}_{\text{REFM}} = 0 \text{ V}$)

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Resolution	RES			8		10	bit
Overall error ^{Note 1}	AINL	10-bit resolution $\text{AV}_{\text{REFP}} = \text{V}_{\text{DD}}$ ^{Note 3}	1.8 V $\leq \text{AV}_{\text{REFP}} \leq 5.5 \text{ V}$		1.2	± 3.5	LSB
			1.6 V $\leq \text{AV}_{\text{REFP}} \leq 5.5 \text{ V}$ ^{Note 4}		1.2	± 7.0	LSB
Conversion time	t _{CONV}	10-bit resolution Target pin: ANI2 to ANI14	3.6 V $\leq \text{V}_{\text{DD}} \leq 5.5 \text{ V}$	2.125		39	μs
			2.7 V $\leq \text{V}_{\text{DD}} \leq 5.5 \text{ V}$	3.1875		39	μs
			1.8 V $\leq \text{V}_{\text{DD}} \leq 5.5 \text{ V}$	17		39	μs
			1.6 V $\leq \text{V}_{\text{DD}} \leq 5.5 \text{ V}$	57		95	μs
	t _{CONV}	10-bit resolution Target pin: Internal reference voltage, and temperature sensor output voltage (HS (high-speed main) mode)	3.6 V $\leq \text{V}_{\text{DD}} \leq 5.5 \text{ V}$	2.375		39	μs
			2.7 V $\leq \text{V}_{\text{DD}} \leq 5.5 \text{ V}$	3.5625		39	μs
			2.4 V $\leq \text{V}_{\text{DD}} \leq 5.5 \text{ V}$	17		39	μs
Zero-scale error ^{Notes 1, 2}	E _{ZS}	10-bit resolution $\text{AV}_{\text{REFP}} = \text{V}_{\text{DD}}$ ^{Note 3}	1.8 V $\leq \text{AV}_{\text{REFP}} \leq 5.5 \text{ V}$			± 0.25	%FSR
			1.6 V $\leq \text{AV}_{\text{REFP}} \leq 5.5 \text{ V}$ ^{Note 4}			± 0.50	%FSR
Full-scale error ^{Notes 1, 2}	E _{FS}	10-bit resolution $\text{AV}_{\text{REFP}} = \text{V}_{\text{DD}}$ ^{Note 3}	1.8 V $\leq \text{AV}_{\text{REFP}} \leq 5.5 \text{ V}$			± 0.25	%FSR
			1.6 V $\leq \text{AV}_{\text{REFP}} \leq 5.5 \text{ V}$ ^{Note 4}			± 0.50	%FSR
Integral linearity error ^{Note 1}	ILE	10-bit resolution $\text{AV}_{\text{REFP}} = \text{V}_{\text{DD}}$ ^{Note 3}	1.8 V $\leq \text{AV}_{\text{REFP}} \leq 5.5 \text{ V}$			± 2.5	LSB
			1.6 V $\leq \text{AV}_{\text{REFP}} \leq 5.5 \text{ V}$ ^{Note 4}			± 5.0	LSB
Differential linearity error ^{Note 1}	DLE	10-bit resolution $\text{AV}_{\text{REFP}} = \text{V}_{\text{DD}}$ ^{Note 3}	1.8 V $\leq \text{AV}_{\text{REFP}} \leq 5.5 \text{ V}$			± 1.5	LSB
			1.6 V $\leq \text{AV}_{\text{REFP}} \leq 5.5 \text{ V}$ ^{Note 4}			± 2.0	LSB
Analog input voltage	V _{AIN}	ANI2 to ANI14		0		AV_{REFP}	V
		Internal reference voltage (2.4 V $\leq \text{V}_{\text{DD}} \leq 5.5 \text{ V}$, HS (high-speed main) mode)			V_{BGR} ^{Note 5}		V
		Temperature sensor output voltage (2.4 V $\leq \text{V}_{\text{DD}} \leq 5.5 \text{ V}$, HS (high-speed main) mode)			V_{TMPS25} ^{Note 5}		V

(Notes are listed on the next page.)

- (3) When reference voltage (+) = V_{DD} ($\text{ADREFP1} = 0$, $\text{ADREFP0} = 0$), reference voltage (-) = V_{SS} ($\text{ADREFM} = 0$), target pin : ANI0 to ANI14, ANI16 to ANI26, internal reference voltage, and temperature sensor output voltage

($T_A = -40$ to $+85^\circ\text{C}$, $1.6 \text{ V} \leq EV_{DD0} = EV_{DD1} \leq V_{DD} \leq 5.5 \text{ V}$, $V_{SS} = EV_{SS0} = EV_{SS1} = 0 \text{ V}$, Reference voltage (+) = V_{DD} , Reference voltage (-) = V_{SS})

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Resolution	RES			8		10	bit
Overall error ^{Note 1}	AINL	10-bit resolution	1.8 V $\leq V_{DD} \leq 5.5 \text{ V}$		1.2	± 7.0	LSB
			1.6 V $\leq V_{DD} \leq 5.5 \text{ V}$ Note 3		1.2	± 10.5	LSB
Conversion time	t _{CONV}	10-bit resolution Target pin: ANI0 to ANI14, ANI16 to ANI26	3.6 V $\leq V_{DD} \leq 5.5 \text{ V}$	2.125		39	μs
			2.7 V $\leq V_{DD} \leq 5.5 \text{ V}$	3.1875		39	μs
			1.8 V $\leq V_{DD} \leq 5.5 \text{ V}$	17		39	μs
			1.6 V $\leq V_{DD} \leq 5.5 \text{ V}$	57		95	μs
Conversion time	t _{CONV}	10-bit resolution Target pin: Internal reference voltage, and temperature sensor output voltage (HS (high-speed main) mode)	3.6 V $\leq V_{DD} \leq 5.5 \text{ V}$	2.375		39	μs
			2.7 V $\leq V_{DD} \leq 5.5 \text{ V}$	3.5625		39	μs
			2.4 V $\leq V_{DD} \leq 5.5 \text{ V}$	17		39	μs
Zero-scale error ^{Notes 1, 2}	E _{ZS}	10-bit resolution	1.8 V $\leq V_{DD} \leq 5.5 \text{ V}$			± 0.60	%FSR
			1.6 V $\leq V_{DD} \leq 5.5 \text{ V}$ Note 3			± 0.85	%FSR
Full-scale error ^{Notes 1, 2}	E _{FS}	10-bit resolution	1.8 V $\leq V_{DD} \leq 5.5 \text{ V}$			± 0.60	%FSR
			1.6 V $\leq V_{DD} \leq 5.5 \text{ V}$ Note 3			± 0.85	%FSR
Integral linearity error ^{Note 1}	ILE	10-bit resolution	1.8 V $\leq V_{DD} \leq 5.5 \text{ V}$			± 4.0	LSB
			1.6 V $\leq V_{DD} \leq 5.5 \text{ V}$ Note 3			± 6.5	LSB
Differential linearity error ^{Note 1}	DLE	10-bit resolution	1.8 V $\leq V_{DD} \leq 5.5 \text{ V}$			± 2.0	LSB
			1.6 V $\leq V_{DD} \leq 5.5 \text{ V}$ Note 3			± 2.5	LSB
Analog input voltage	V _{AIN}	ANI0 to ANI14		0		V_{DD}	V
		ANI16 to ANI26		0		EV_{DD0}	V
		Internal reference voltage (2.4 V $\leq V_{DD} \leq 5.5 \text{ V}$, HS (high-speed main) mode)		V_{BGR} ^{Note 4}			V
		Temperature sensor output voltage (2.4 V $\leq V_{DD} \leq 5.5 \text{ V}$, HS (high-speed main) mode)		V_{TMPS25} ^{Note 4}			V

- Notes**
- Excludes quantization error ($\pm 1/2$ LSB).
 - This value is indicated as a ratio (%FSR) to the full-scale value.
 - When the conversion time is set to 57 μs (min.) and 95 μs (max.).
 - Refer to **2.6.2 Temperature sensor/internal reference voltage characteristics**.

Remark The electrical characteristics of the products G: Industrial applications ($T_A = -40$ to $+105^\circ\text{C}$) are different from those of the products "A: Consumer applications, and D: Industrial applications". For details, refer to **3.1 to 3.10**.

3.1 Absolute Maximum Ratings

Absolute Maximum Ratings ($T_A = 25^\circ\text{C}$) (1/2)

Parameter	Symbols	Conditions	Ratings	Unit
Supply voltage	V_{DD}		-0.5 to +6.5	V
	EV_{DD0}, EV_{DD1}	$EV_{DD0} = EV_{DD1}$	-0.5 to +6.5	V
	EV_{SS0}, EV_{SS1}	$EV_{SS0} = EV_{SS1}$	-0.5 to +0.3	V
REGC pin input voltage	V_{IREGC}	REGC	-0.3 to +2.8 and -0.3 to $V_{DD} + 0.3^{\text{Note 1}}$	V
Input voltage	V_{I1}	P00 to P07, P10 to P17, P30 to P37, P40 to P47, P50 to P57, P64 to P67, P70 to P77, P80 to P87, P90 to P97, P100 to P106, P110 to P117, P120, P125 to P127, P140 to P147	-0.3 to $EV_{DD0} + 0.3$ and -0.3 to $V_{DD} + 0.3^{\text{Note 2}}$	V
	V_{I2}	P60 to P63 (N-ch open-drain)	-0.3 to +6.5	V
	V_{I3}	P20 to P27, P121 to P124, P137, P150 to P156, EXCLK, EXCLKS, RESET	-0.3 to $V_{DD} + 0.3^{\text{Note 2}}$	V
Output voltage	V_{O1}	P00 to P07, P10 to P17, P30 to P37, P40 to P47, P50 to P57, P60 to P67, P70 to P77, P80 to P87, P90 to P97, P100 to P106, P110 to P117, P120, P125 to P127, P130, P140 to P147	-0.3 to $EV_{DD0} + 0.3$ and -0.3 to $V_{DD} + 0.3^{\text{Note 2}}$	V
	V_{O2}	P20 to P27, P150 to P156	-0.3 to $V_{DD} + 0.3^{\text{Note 2}}$	V
Analog input voltage	V_{AI1}	ANI16 to ANI26	-0.3 to $EV_{DD0} + 0.3$ and -0.3 to $AV_{REF}(+) + 0.3^{\text{Notes 2, 3}}$	V
	V_{AI2}	ANIO to ANI14	-0.3 to $V_{DD} + 0.3$ and -0.3 to $AV_{REF}(+) + 0.3^{\text{Notes 2, 3}}$	V

- Notes 1.** Connect the REGC pin to Vss via a capacitor (0.47 to 1 μF). This value regulates the absolute maximum rating of the REGC pin. Do not use this pin with voltage applied to it.
2. Must be 6.5 V or lower.
 3. Do not exceed $AV_{REF}(+) + 0.3$ V in case of A/D conversion target pin.

Caution Product quality may suffer if the absolute maximum rating is exceeded even momentarily for any parameter. That is, the absolute maximum ratings are rated values at which the product is on the verge of suffering physical damage, and therefore the product must be used under conditions that ensure that the absolute maximum ratings are not exceeded.

- Remarks**
1. Unless specified otherwise, the characteristics of alternate-function pins are the same as those of the port pins.
 2. $AV_{REF}(+)$: + side reference voltage of the A/D converter.
 3. V_{ss} : Reference voltage

(5) Communication at different potential (1.8 V, 2.5 V, 3 V) (UART mode) (2/2)

(TA = -40 to +105°C, 2.4 V ≤ EV_{DD0} = EV_{DD1} ≤ V_{DD} ≤ 5.5 V, V_{SS} = EV_{SS0} = EV_{SS1} = 0 V)

Parameter	Symbol	Conditions		HS (high-speed main) Mode		Unit
				MIN.	MAX.	
Transfer rate	Transmission	4.0 V ≤ EV _{DD0} ≤ 5.5 V, 2.7 V ≤ V _b ≤ 4.0 V	Theoretical value of the maximum transfer rate C _b = 50 pF, R _b = 1.4 kΩ, V _b = 2.7 V		Note 1	bps
		2.7 V ≤ EV _{DD0} < 4.0 V, 2.3 V ≤ V _b ≤ 2.7 V	Theoretical value of the maximum transfer rate C _b = 50 pF, R _b = 2.7 kΩ, V _b = 2.3 V		Note 3	bps
		2.4 V ≤ EV _{DD0} < 3.3 V, 1.6 V ≤ V _b ≤ 2.0 V	Theoretical value of the maximum transfer rate C _b = 50 pF, R _b = 5.5 kΩ, V _b = 1.6 V		Note 5	bps

Notes 1. The smaller maximum transfer rate derived by using f_{MCK}/12 or the following expression is the valid maximum transfer rate.

Expression for calculating the transfer rate when 4.0 V ≤ EV_{DD0} ≤ 5.5 V and 2.7 V ≤ V_b ≤ 4.0 V

$$\text{Maximum transfer rate} = \frac{1}{\{-C_b \times R_b \times \ln(1 - \frac{2.2}{V_b})\} \times 3} \text{ [bps]}$$

$$\text{Baud rate error (theoretical value)} = \frac{\frac{1}{\text{Transfer rate} \times 2} - \{-C_b \times R_b \times \ln(1 - \frac{2.2}{V_b})\}}{\frac{1}{(\text{Transfer rate})} \times \text{Number of transferred bits}} \times 100 [\%]$$

* This value is the theoretical value of the relative difference between the transmission and reception sides.

2. This value as an example is calculated when the conditions described in the “Conditions” column are met. Refer to Note 1 above to calculate the maximum transfer rate under conditions of the customer.
3. The smaller maximum transfer rate derived by using f_{MCK}/12 or the following expression is the valid maximum transfer rate.

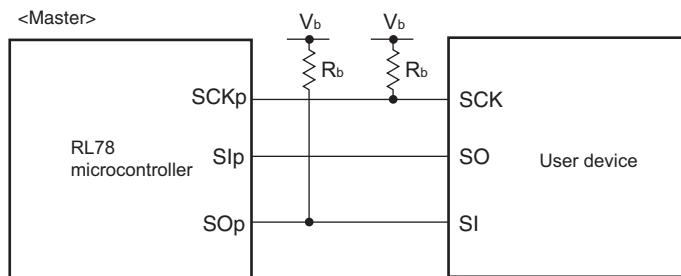
Expression for calculating the transfer rate when 2.7 V ≤ EV_{DD0} < 4.0 V and 2.4 V ≤ V_b ≤ 2.7 V

$$\text{Maximum transfer rate} = \frac{1}{\{-C_b \times R_b \times \ln(1 - \frac{2.0}{V_b})\} \times 3} \text{ [bps]}$$

$$\text{Baud rate error (theoretical value)} = \frac{\frac{1}{\text{Transfer rate} \times 2} - \{-C_b \times R_b \times \ln(1 - \frac{2.0}{V_b})\}}{\frac{1}{(\text{Transfer rate})} \times \text{Number of transferred bits}} \times 100 [\%]$$

* This value is the theoretical value of the relative difference between the transmission and reception sides.

4. This value as an example is calculated when the conditions described in the “Conditions” column are met. Refer to Note 3 above to calculate the maximum transfer rate under conditions of the customer.

CSI mode connection diagram (during communication at different potential)

- Remarks**
1. $R_b[\Omega]$: Communication line (SCKp, SOp) pull-up resistance, $C_b[F]$: Communication line (SCKp, SOp) load capacitance, $V_b[V]$: Communication line voltage
 2. p: CSI number ($p = 00, 01, 10, 20, 30, 31$), m: Unit number , n: Channel number ($mn = 00, 01, 02, 10, 12, 13$), g: PIM and POM number ($g = 0, 1, 4, 5, 8, 14$)
 3. fmck: Serial array unit operation clock frequency
(Operation clock to be set by the CKSmn bit of serial mode register mn (SMRmn).
m: Unit number, n: Channel number ($mn = 00$))
 4. CSI01 of 48-, 52-, 64-pin products, and CSI11 and CSI21 cannot communicate at different potential.
Use other CSI for communication at different potential.

3.5.2 Serial interface IICA

($T_A = -40$ to $+105^\circ\text{C}$, $2.4 \text{ V} \leq EV_{DD0} = EV_{DD1} \leq V_{DD} \leq 5.5 \text{ V}$, $V_{SS} = EV_{SS0} = EV_{SS1} = 0 \text{ V}$)

Parameter	Symbol	Conditions	HS (high-speed main) Mode				Unit	
			Standard Mode		Fast Mode			
			MIN.	MAX.	MIN.	MAX.		
SCLA0 clock frequency	f_{SCL}	Fast mode: $f_{CLK} \geq 3.5 \text{ MHz}$	—	—	0	400	kHz	
		Standard mode: $f_{CLK} \geq 1 \text{ MHz}$	0	100	—	—	kHz	
Setup time of restart condition	$t_{SU:STA}$		4.7		0.6		μs	
Hold time ^{Note 1}	$t_{HD:STA}$		4.0		0.6		μs	
Hold time when SCLA0 = "L"	t_{LOW}		4.7		1.3		μs	
Hold time when SCLA0 = "H"	t_{HIGH}		4.0		0.6		μs	
Data setup time (reception)	$t_{SU:DAT}$		250		100		ns	
Data hold time (transmission) ^{Note 2}	$t_{HD:DAT}$		0	3.45	0	0.9	μs	
Setup time of stop condition	$t_{SU:STO}$		4.0		0.6		μs	
Bus-free time	t_{BUF}		4.7		1.3		μs	

Notes 1. The first clock pulse is generated after this period when the start/restart condition is detected.

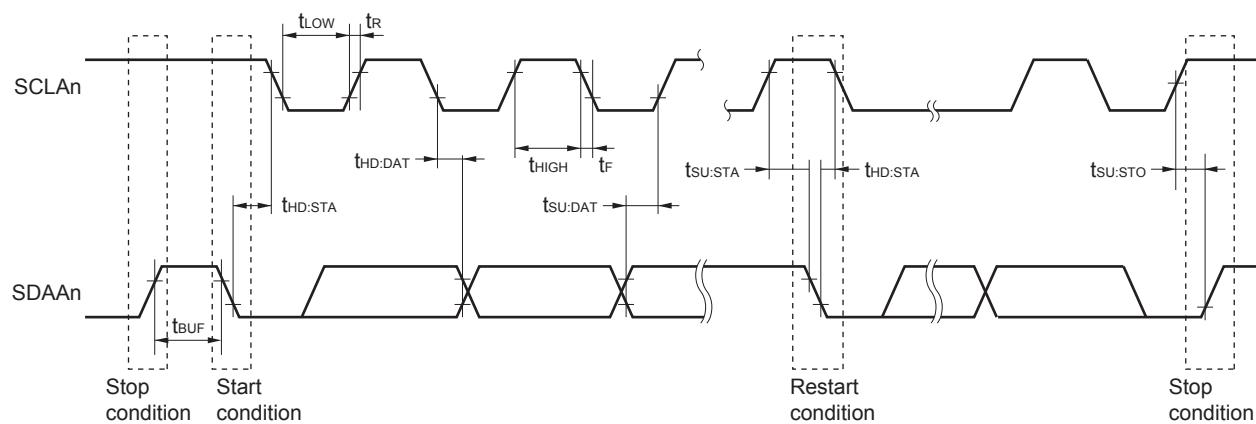
<R> 2. The maximum value (MAX.) of $t_{HD:DAT}$ is during normal transfer and a wait state is inserted in the ACK (acknowledge) timing.

Caution The values in the above table are applied even when bit 2 (PIOR2) in the peripheral I/O redirection register (PIOR) is 1. At this time, the pin characteristics (I_{OH1} , I_{OL1} , V_{OH1} , V_{OL1}) must satisfy the values in the redirect destination.

Remark The maximum value of C_b (communication line capacitance) and the value of R_b (communication line pull-up resistor) at that time in each mode are as follows.

Standard mode: $C_b = 400 \text{ pF}$, $R_b = 2.7 \text{ k}\Omega$
 Fast mode: $C_b = 320 \text{ pF}$, $R_b = 1.1 \text{ k}\Omega$

IICA serial transfer timing



Remark $n = 0, 1$

- (3) When reference voltage (+) = V_{DD} (ADREFP1 = 0, ADREFP0 = 0), reference voltage (-) = V_{SS} (ADREFM = 0), target pin : ANI0 to ANI14, ANI16 to ANI26, internal reference voltage, and temperature sensor output voltage

(TA = -40 to +105°C, 2.4 V ≤ EV_{DD0} = EV_{DD1} ≤ V_{DD} ≤ 5.5 V, V_{SS} = EV_{SS0} = EV_{SS1} = 0 V, Reference voltage (+) = V_{DD}, Reference voltage (-) = V_{SS})

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Resolution	RES			8		10	bit
Overall error ^{Note 1}	AINL	10-bit resolution	2.4 V ≤ V _{DD} ≤ 5.5 V		1.2	±7.0	LSB
Conversion time	t _{CONV}	10-bit resolution	3.6 V ≤ V _{DD} ≤ 5.5 V	2.125		39	μs
		Target pin: ANI0 to ANI14, ANI16 to ANI26	2.7 V ≤ V _{DD} ≤ 5.5 V	3.1875		39	μs
		2.4 V ≤ V _{DD} ≤ 5.5 V	17		39	μs	
		10-bit resolution	3.6 V ≤ V _{DD} ≤ 5.5 V	2.375		39	μs
		Target pin: Internal reference voltage, and temperature sensor output voltage (HS (high-speed main) mode)	2.7 V ≤ V _{DD} ≤ 5.5 V	3.5625		39	μs
		2.4 V ≤ V _{DD} ≤ 5.5 V	17		39	μs	
Zero-scale error ^{Notes 1, 2}	E _{ZS}	10-bit resolution	2.4 V ≤ V _{DD} ≤ 5.5 V			±0.60	%FSR
Full-scale error ^{Notes 1, 2}	E _{FS}	10-bit resolution	2.4 V ≤ V _{DD} ≤ 5.5 V			±0.60	%FSR
Integral linearity error ^{Note 1}	ILE	10-bit resolution	2.4 V ≤ V _{DD} ≤ 5.5 V			±4.0	LSB
Differential linearity error ^{Note 1}	DLE	10-bit resolution	2.4 V ≤ V _{DD} ≤ 5.5 V			±2.0	LSB
Analog input voltage	V _{AIN}	ANI0 to ANI14		0		V _{DD}	V
		ANI16 to ANI26		0		EV _{DD0}	V
		Internal reference voltage output (2.4 V ≤ V _{DD} ≤ 5.5 V, HS (high-speed main) mode)			V _{BGR} ^{Note 3}		V
		Temperature sensor output voltage (2.4 V ≤ V _{DD} ≤ 5.5 V, HS (high-speed main) mode)			V _{TMP525} ^{Note 3}		V

Notes 1. Excludes quantization error (±1/2 LSB).

2. This value is indicated as a ratio (%FSR) to the full-scale value.

3. Refer to 3.6.2 Temperature sensor/internal reference voltage characteristics.

3.6.5 Power supply voltage rising slope characteristics

($T_A = -40$ to $+105^\circ\text{C}$, $V_{SS} = 0$ V)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Power supply voltage rising slope	S_{VDD}				54	V/ms

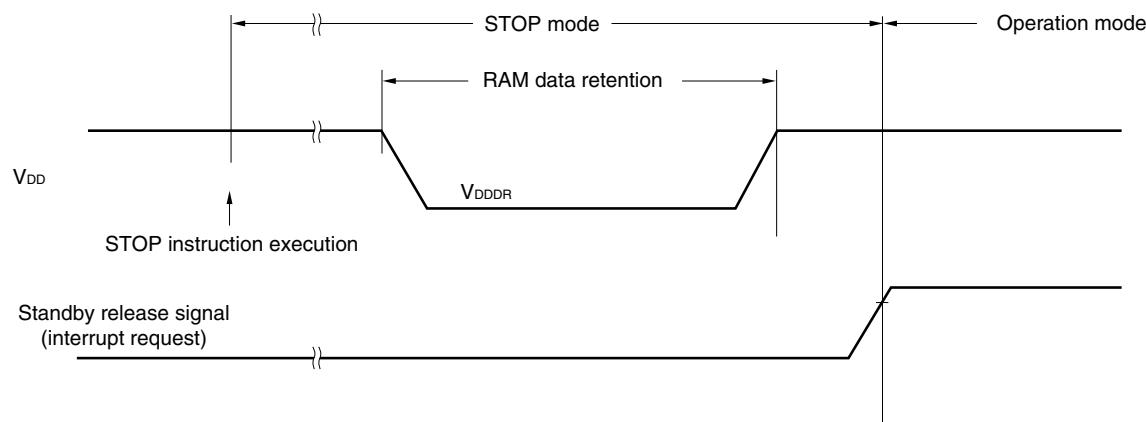
Caution Make sure to keep the internal reset state by the LVD circuit or an external reset until V_{DD} reaches the operating voltage range shown in 3.4 AC Characteristics.

3.7 RAM Data Retention Characteristics

($T_A = -40$ to $+105^\circ\text{C}$, $V_{SS} = 0$ V)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Data retention supply voltage	V_{DDDR}		1.44 ^{Note}		5.5	V

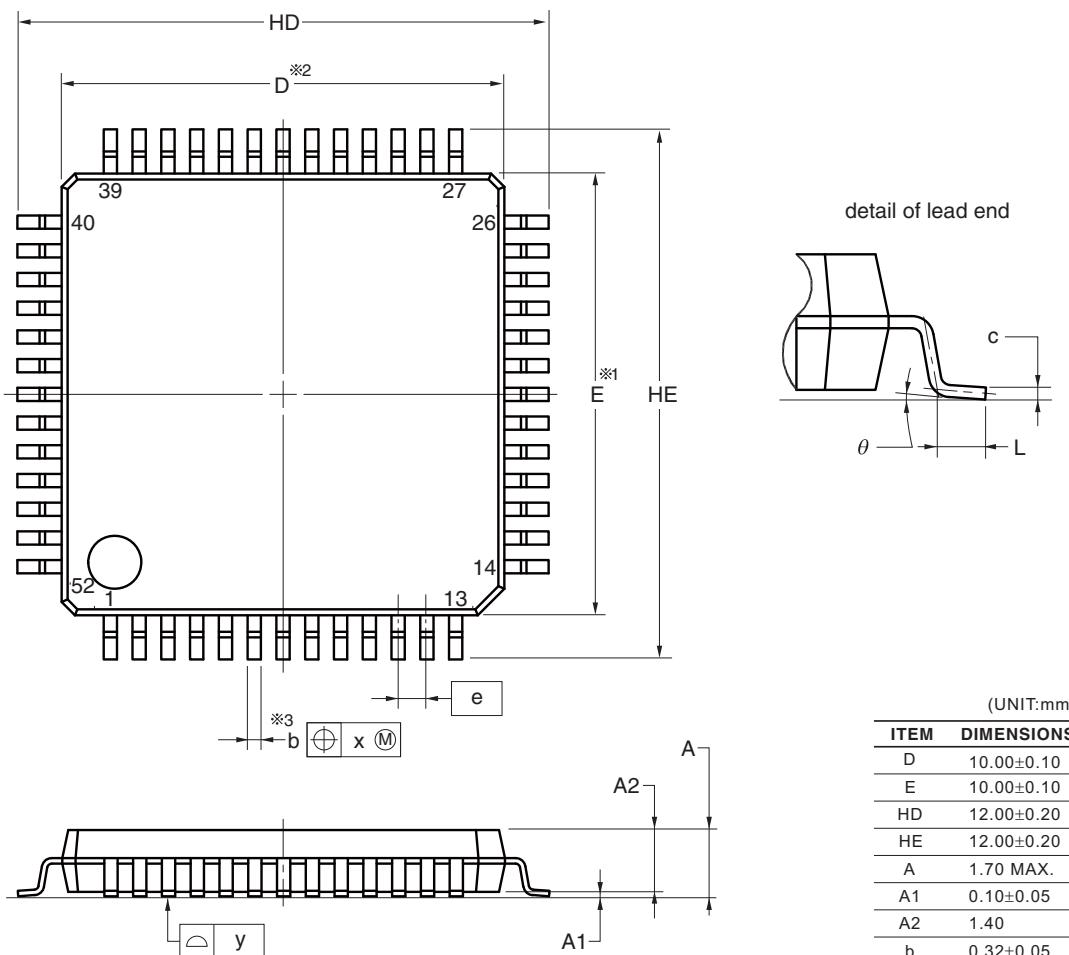
Note This depends on the POR detection voltage. For a falling voltage, data in RAM are retained until the voltage reaches the level that triggers a POR reset but not once it reaches the level at which a POR reset is generated.



4.10 52-pin Products

R5F100JCAFA, R5F100JDAFA, R5F100JEAF, R5F100JFAFA, R5F100JGAF, R5F100JHAF, R5F100JJAF,
 R5F100JKAF, R5F100JLAF
 R5F101JCAFA, R5F101JDAFA, R5F101JEAF, R5F101JFAFA, R5F101JGAF, R5F101JHAF, R5F101JJAF,
 R5F101JKAF, R5F101JLAF
 R5F100JCDFA, R5F100JDDFA, R5F100JEDFA, R5F100JFDFA, R5F100JGDFA, R5F100JHDFA, R5F100JJDF,
 R5F100JKDFA, R5F100JLDFA
 R5F101JCDFA, R5F101JDDFA, R5F101JEDFA, R5F101JFDFA, R5F101JGDFA, R5F101JHDFA, R5F101JJDF,
 R5F101JKDFA, R5F101JLDFA
 R5F100JCGFA, R5F100JDGFA, R5F100JEGFA, R5F100JFGFA, R5F100JGGFA, R5F100JHGFA, R5F100JJGFA

JEITA Package Code	RENESAS Code	Previous Code	MASS (TYP.) [g]
P-LQFP52-10x10-0.65	PLQP0052JA-A	P52GB-65-GBS-1	0.3



(UNIT:mm)	
ITEM	DIMENSIONS
D	10.00±0.10
E	10.00±0.10
HD	12.00±0.20
HE	12.00±0.20
A	1.70 MAX.
A1	0.10±0.05
A2	1.40
b	0.32±0.05
c	0.145±0.055
L	0.50±0.15
θ	0° to 8°
e	0.65
x	0.13
y	0.10

NOTE

1. Dimensions “*1” and “*2” do not include mold flash.
2. Dimension “*3” does not include trim offset.

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